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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	56800E
Core Size	16-Bit
Speed	60MHz
Connectivity	CANbus, EBI/EMI, SCI, SPI
Peripherals	POR, PWM, Temp Sensor, WDT
Number of I/O	76
Program Memory Size	256KB (128K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	10K x 16
Voltage - Supply (Vcc/Vdd)	2.25V ~ 3.6V
Data Converters	A/D 16x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	160-LQFP
Supplier Device Package	160-LQFP (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc56f8357mpye

Part 1 Overview

1.1 56F8357/56F8157 Features

1.1.1 Core

- Efficient 16-bit 56800E family controller engine with dual Harvard architecture
- Up to 60 Million Instructions Per Second (MIPS) at 60 MHz core frequency
- Single-cycle 16 × 16-bit parallel Multiplier-Accumulator (MAC)
- Four 36-bit accumulators, including extension bits
- Arithmetic and logic multi-bit shifter
- Parallel instruction set with unique DSP addressing modes
- Hardware DO and REP loops
- Three internal address buses
- Four internal data buses
- Instruction set supports both DSP and controller functions
- Controller-style addressing modes and instructions for compact code
- Efficient C compiler and local variable support
- Software subroutine and interrupt stack with depth limited only by memory
- JTAG/EOnCE debug programming interface

1.1.2 Differences Between Devices

Table 1-1 outlines the key differences between the 56F8357 and 56F8157 devices.

Table 1-1 Device Differences

Feature	56F8357	56F8157
Guaranteed Speed	60MHz/60 MIPS	40MHz/40 MIPS
Program RAM	4KB	Not Available
Data Flash	8KB	Not Available
PWM	2 x 6	1 x 6
CAN	1	Not Available
Quad Timer	4	2
Quadrature Decoder	2 x 4	1 x 4
Temperature Sensor	1	Not Available
Dedicated GPIO	—	7

1.4 Architecture Block Diagram

Note: *Features in italics are NOT available in the 56F8157 device and are shaded in the following figures.*

The 56F8357/56F8157 architecture is shown in **Figure 1-1** and **Figure 1-2**. **Figure 1-1** illustrates how the 56800E system buses communicate with internal memories, the external memory interface and the IPBus Bridge. **Table 1-2** lists the internal buses in the 56800E architecture and provides a brief description of their function. **Figure 1-2** shows the peripherals and control blocks connected to the IPBus Bridge. The figures do not show the on-board regulator and power and ground signals. They also do not show the multiplexing between peripherals or the dedicated GPIOs. Please see **Part 2, Signal/Connection Descriptions,** to see which signals are multiplexed with those of other peripherals.

Also shown in **Figure 1-2** are connections between the PWM, Timer C and ADC blocks. These connections allow the PWM and/or Timer C to control the timing of the start of ADC conversions. The Timer C channel indicated can generate periodic start (SYNC) signals to the ADC to start its conversions. In another operating mode, the PWM load interrupt (SYNC output) signal is routed internally to the Timer C input channel as indicated. The timer can then be used to introduce a controllable delay before generating its output signal. The timer output then triggers the ADC. To fully understand this interaction, please see the **56F8300 Peripheral User Manual** for clarification on the operation of all three of these peripherals.

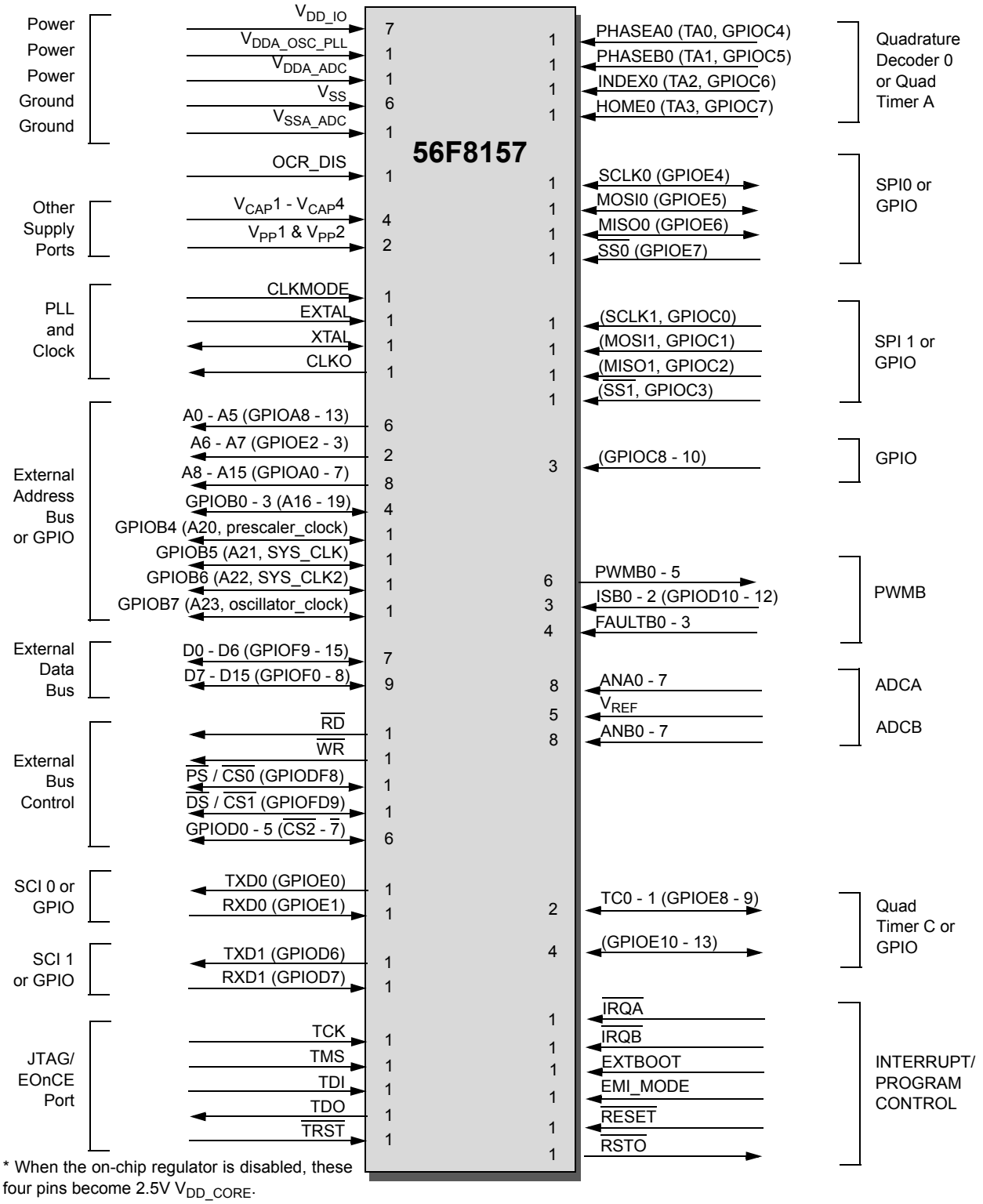

Figure 2-2 56F8157 Signals Identified by Functional Group[1] (160-pin LQFP)

1. Alternate pin functionality is shown in parenthesis; pin direction/type shown is the default functionality.

Table 2-2 Signal and Package Information for the 160-Pin LQFP and MBGA

Signal Name	Pin No.	*Ball No.*	Type	State During Reset	Signal Description
TXD1 **(GPIOD6)**	49	P4	Output Input/ Output	In reset, output is disabled, pull-up is enabled	**Transmit Data** — SCI1 transmit data output **Port D GPIO** — This GPIO pin can be individually programmed as an input or output pin. After reset, the default state is SCI output. To deactivate the internal pull-up resistor, clear bit 6 in the GPIOD_PUR register.
RXD1 **(GPIOD7)**	50	N5	Input Input/ Output	Input, pull-up enabled	**Receive Data** — SCI1 receive data input **Port D GPIO** — This GPIO pin can be individually programmed as an input or output pin. After reset, the default state is SCI input. To deactivate the internal pull-up resistor, clear bit 7 in the GPIOD_PUR register.
TCK	137	D8	Schmitt Input	Input, pulled low internally	**Test Clock Input** — This input pin provides a gated clock to synchronize the test logic and shift serial data to the JTAG/EOnCE port. The pin is connected internally to a pull-down resistor.
TMS	138	A8	Schmitt Input	Input, pulled high internally	**Test Mode Select Input** — This input pin is used to sequence the JTAG TAP controller's state machine. It is sampled on the rising edge of TCK and has an on-chip pull-up resistor. To deactivate the internal pull-up resistor, set the JTAG bit in the SIM_PUDR register. **Note:** Always tie the TMS pin to V_{DD} through a 2.2K resistor.
TDI	139	B8	Schmitt Input	Input, pulled high internally	**Test Data Input** — This input pin provides a serial input data stream to the JTAG/EOnCE port. It is sampled on the rising edge of TCK and has an on-chip pull-up resistor. To deactivate the internal pull-up resistor, set the JTAG bit in the SIM_PUDR register.
TDO	140	D7	Output	In reset, output is disabled, pull-up is enabled	**Test Data Output** — This tri-stateable output pin provides a serial output data stream from the JTAG/EOnCE port. It is driven in the shift-IR and shift-DR controller states, and changes on the falling edge of TCK.

Table 2-2 Signal and Package Information for the 160-Pin LQFP and MBGA

Signal Name	Pin No.	*Ball No.*	Type	State During Reset	Signal Description
PHASEA1	6	C1	Schmitt Input	Input, pull-up enabled	**Phase A1** — Quadrature Decoder 1, PHASEA input for decoder 1.
(TB0)			Schmitt Input/ Output		**TB0** — Timer B, Channel 0
(SCLK1)			Schmitt Input/ Output		**SPI 1 Serial Clock** — In the master mode, this pin serves as an output, clocking slaved listeners. In slave mode, this pin serves as the data clock input. To activate the SPI function, set the PHSA_ALT bit in the SIM_GPS register. For details, see Part 6.5.8.
(GPIOC0)			Schmitt Input/ Output		**Port C GPIO** — This GPIO pin can be individually programmed as an input or output pin. In the 56F8357, the default state after reset is PHASEA1. In the 56F8157, the default state is not one of the functions offered and must be reconfigured. To deactivate the internal pull-up resistor, clear bit 0 in the GPIOC_PUR register.
PHASEB1	7	D1	Schmitt Input	Input, pull-up enabled	**Phase B1** — Quadrature Decoder ,1 PHASEB input for decoder 1.
(TB1)			Schmitt Input/ Output		**TB1** — Timer B, Channel 1
(MOSI1)			Schmitt Input/ Output		**SPI 1 Master Out/Slave In** — This serial data pin is an output from a master device and an input to a slave device. The master device places data on the MOSI line a half-cycle before the clock edge the slave device uses to latch the data. To activate the SPI function, set the PHSB_ALT bit in the SIM_GPS register. For details, see Part 6.5.8.
(GPIOC1)			Schmitt Input/ Output		**Port C GPIO** — This GPIO pin can be individually programmed as an input or output pin. In the 56F8357, the default state after reset is PHASEB1. In the 56F8157, the default state is not one of the functions offered and must be reconfigured. To deactivate the internal pull-up resistor, clear bit 1 in the GPIOC_PUR register.

Table 4-14 Quad Timer D Registers Address Map (Continued)
(TMRD_BASE = $00 F100)
Quad Timer D is NOT available in the 56F8157 device

Register Acronym	Address Offset	Register Description
TMRD1_COMSCR	$1A	Comparator Status and Control Register
		Reserved
TMRD2_CMP1	$20	Compare Register 1
TMRD2_CMP2	$21	Compare Register 2
TMRD2_CAP	$22	Capture Register
TMRD2_LOAD	$23	Load Register
TMRD2_HOLD	$24	Hold Register
TMRD2_CNTR	$25	Counter Register
TMRD2_CTRL	$26	Control Register
TMRD2_SCR	$27	Status and Control Register
TMRD2_CMPLD1	$28	Comparator Load Register 1
TMRD2_CMPLD2	$29	Comparator Load Register 2
TMRD2_COMSCR	$2A	Comparator Status and Control Register
		Reserved
TMRD3_CMP1	$30	Compare Register 1
TMRD3_CMP2	$31	Compare Register 2
TMRD3_CAP	$32	Capture Register
TMRD3_LOAD	$33	Load Register
TMRD3_HOLD	$34	Hold Register
TMRD3_CNTR	$35	Counter Register
TMRD3_CTRL	$36	Control Register
TMRD3_SCR	$37	Status and Control Register
TMRD3_CMPLD1	$38	Comparator Load Register 1
TMRD3_CMPLD2	$39	Comparator Load Register 2
TMRD3_COMSCR	$3A	Comparator Status and Control Register

Table 4-20 Analog-to-Digital Converter Registers Address Map (Continued) (ADCA_BASE = $00 F200)

Register Acronym	Address Offset	Register Description
ADCA_LLMT 2	$13	Low Limit Register 2
ADCA_LLMT 3	$14	Low Limit Register 3
ADCA_LLMT 4	$15	Low Limit Register 4
ADCA_LLMT 5	$16	Low Limit Register 5
ADCA_LLMT 6	$17	Low Limit Register 6
ADCA_LLMT 7	$18	Low Limit Register 7
ADCA_HLMT 0	$19	High Limit Register 0
ADCA_HLMT 1	$1A	High Limit Register 1
ADCA_HLMT 2	$1B	High Limit Register 2
ADCA_HLMT 3	$1C	High Limit Register 3
ADCA_HLMT 4	$1D	High Limit Register 4
ADCA_HLMT 5	$1E	High Limit Register 5
ADCA_HLMT 6	$1F	High Limit Register 6
ADCA_HLMT 7	$20	High Limit Register 7
ADCA_OFS 0	$21	Offset Register 0
ADCA_OFS 1	$22	Offset Register 1
ADCA_OFS 2	$23	Offset Register 2
ADCA_OFS 3	$24	Offset Register 3
ADCA_OFS 4	$25	Offset Register 4
ADCA_OFS 5	$26	Offset Register 5
ADCA_OFS 6	$27	Offset Register 6
ADCA_OFS 7	$28	Offset Register 7
ADCA_POWER	$29	Power Control Register
ADCA_CAL	$2A	ADC Calibration Register

Table 4-38 FlexCAN Registers Address Map (Continued)
(FC_BASE = $00 F800)
FlexCAN is NOT available in the 56F8157 device

Register Acronym	Address Offset	Register Description
FCMSB1_ID_LOW	$4A	Message Buffer 1 ID Low Register
FCMB1_DATA	$4B	Message Buffer 1 Data Register
FCMB1_DATA	$4C	Message Buffer 1 Data Register
FCMB1_DATA	$4D	Message Buffer 1 Data Register
FCMB1_DATA	$4E	Message Buffer 1 Data Register
		Reserved
FCMB2_CONTROL	$50	Message Buffer 2 Control / Status Register
FCMB2_ID_HIGH	$51	Message Buffer 2 ID High Register
FCMB2_ID_LOW	$52	Message Buffer 2 ID Low Register
FCMB2_DATA	$53	Message Buffer 2 Data Register
FCMB2_DATA	$54	Message Buffer 2 Data Register
FCMB2_DATA	$55	Message Buffer 2 Data Register
FCMB2_DATA	$56	Message Buffer 2 Data Register
		Reserved
FCMB3_CONTROL	$58	Message Buffer 3 Control / Status Register
FCMB3_ID_HIGH	$59	Message Buffer 3 ID High Register
FCMB3_ID_LOW	$5A	Message Buffer 3 ID Low Register
FCMB3_DATA	$5B	Message Buffer 3 Data Register
FCMB3_DATA	$5C	Message Buffer 3 Data Register
FCMB3_DATA	$5D	Message Buffer 3 Data Register
FCMB3_DATA	$5E	Message Buffer 3 Data Register
		Reserved
FCMB4_CONTROL	$60	Message Buffer 4 Control / Status Register
FCMB4_ID_HIGH	$61	Message Buffer 4 ID High Register
FCMB4_ID_LOW	$62	Message Buffer 4 ID Low Register
FCMB4_DATA	$63	Message Buffer 4 Data Register
FCMB4_DATA	$64	Message Buffer 4 Data Register
FCMB4_DATA	$65	Message Buffer 4 Data Register
FCMB4_DATA	$66	Message Buffer 4 Data Register
		Reserved
FCMB5_CONTROL	$68	Message Buffer 5 Control / Status Register

Table 4-38 FlexCAN Registers Address Map (Continued)
(FC_BASE = $00 F800)
FlexCAN is NOT available in the 56F8157 device

Register Acronym	Address Offset	Register Description
FCMB5_ID_HIGH	$69	Message Buffer 5 ID High Register
FCMB5_ID_LOW	$6A	Message Buffer 5 ID Low Register
FCMB5_DATA	$6B	Message Buffer 5 Data Register
FCMB5_DATA	$6C	Message Buffer 5 Data Register
FCMB5_DATA	$6D	Message Buffer 5 Data Register
FCMB5_DATA	$6E	Message Buffer 5 Data Register
		Reserved
FCMB6_CONTROL	$70	Message Buffer 6 Control / Status Register
FCMB6_ID_HIGH	$71	Message Buffer 6 ID High Register
FCMB6_ID_LOW	$72	Message Buffer 6 ID Low Register
FCMB6_DATA	$73	Message Buffer 6 Data Register
FCMB6_DATA	$74	Message Buffer 6 Data Register
FCMB6_DATA	$75	Message Buffer 6 Data Register
FCMB6_DATA	$76	Message Buffer 6 Data Register
		Reserved
FCMB7_CONTROL	$78	Message Buffer 7 Control / Status Register
FCMB7_ID_HIGH	$79	Message Buffer 7 ID High Register
FCMB7_ID_LOW	$7A	Message Buffer 7 ID Low Register
FCMB7_DATA	$7B	Message Buffer 7 Data Register
FCMB7_DATA	$7C	Message Buffer 7 Data Register
FCMB7_DATA	$7D	Message Buffer 7 Data Register
FCMB7_DATA	$7E	Message Buffer 7 Data Register
		Reserved
FCMB8_CONTROL	$80	Message Buffer 8 Control / Status Register
FCMB8_ID_HIGH	$81	Message Buffer 8 ID High Register
FCMB8_ID_LOW	$82	Message Buffer 8 ID Low Register
FCMB8_DATA	$83	Message Buffer 8 Data Register
FCMB8_DATA	$84	Message Buffer 8 Data Register
FCMB8_DATA	$85	Message Buffer 8 Data Register
FCMB8_DATA	$86	Message Buffer 8 Data Register
		Reserved

5.6.3.5 Low Voltage Detector Interrupt Priority Level (LVI IPL)—Bits 7–6

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.3.6 Reserved—Bits 5–4

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.3.7 External IRQ B Interrupt Priority Level (IRQB IPL)—Bits 3–2

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.3.8 External IRQ A Interrupt Priority Level (IRQA IPL)—Bits 1–0

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.4 Interrupt Priority Register 3 (IPR3)

Base + $3	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	GPIOD IPL		GPIOE IPL		GPIOF IPL		FCMSGBUF IPL		FCWKUP IPL		FCERR IPL		FCBOFF IPL		0	0
Write																
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-6 Interrupt Priority Register 3 (IPR3)

5.6.6.3 SCI1 Receiver Full Interrupt Priority Level (SCI1_RCV IPL)—Bits 11–10

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.6.4 SCI1 Receiver Error Interrupt Priority Level (SCI1_RERR IPL)—Bits 9–8

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.6.5 Reserved—Bits 7–6

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.6.6 SCI1 Transmitter Idle Interrupt Priority Level (SCI1_TIDL IPL)—Bits 5–4

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.6.7 SCI1 Transmitter Empty Interrupt Priority Level (SCI1_XMIT IPL)— Bits 3–2

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

6.5.9.7 Quad Timer D Enable (TMRD)—Bit 9

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 = The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.8 Quad Timer C Enable (TMRC)—Bit 8

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 = The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.9 Quad Timer B Enable (TMRB)—Bit 7

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 = The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.10 Quad Timer A Enable (TMRA)—Bit 6

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 = The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.11 Serial Communications Interface 1 Enable (SCI1)—Bit 5

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 = The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.12 Serial Communications Interface 0 Enable (SCI0)—Bit 4

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 = The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.13 Serial Peripheral Interface 1 Enable (SPI1)—Bit 3

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 = The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.14 Serial Peripheral Interface 0 Enable (SPI0)—Bit 2

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 = The clock is not provided to the peripheral (the peripheral is disabled)

Table 10-8 Current Consumption per Power Supply Pin (Typical)
On-Chip Regulator Disabled (OCR_DIS = High)

Mode	I_{DD_Core}	I_{DD_IO}[1]	I_{DD_ADC}	$I_{DD\_OSC\_PLL}$	Test Conditions
RUN1_MAC	150mA	13µA	50mA	2.5mA	• 60MHz Device Clock • All peripheral clocks are enabled • All peripherals running • Continuous MAC instructions with fetches from Data RAM • ADC powered on and clocked
Wait3	86mA	13µA	70µA	2.5mA	• 60MHz Device Clock • All peripheral clocks are enabled • ADC powered off
Stop1	900µA	13µA	0µA	155µA	• 8MHz Device Clock • All peripheral clocks are off • ADC powered off • PLL powered off
Stop2	100µA	13µA	0µA	145µA	• External Clock is off • All peripheral clocks are off • ADC powered off • PLL powered off

1. No Output Switching

Table 10-9. Regulator Parameters

Characteristic	Symbol	Min	Typical	Max	Unit
Unloaded Output Voltage (0mA Load)	V_{RNL}	2.25	—	2.75	V
Loaded Output Voltage (200 mA load)	V_{RL}	2.25	—	2.75	V
Line Regulation @ 250 mA load ($V_{DD}33$ ranges from 3.0 to 3.6)	V_R	2.25	—	2.75	V
Short Circuit Current (output shorted to ground)	Iss	—	—	700	mA
Bias Current	I_{bias}	—	5.8	7	mA
Power-down Current	I_{pd}	—	0	2	µA
Short-Circuit Tolerance (output shorted to ground)	T_{RSC}	—	—	30	minutes

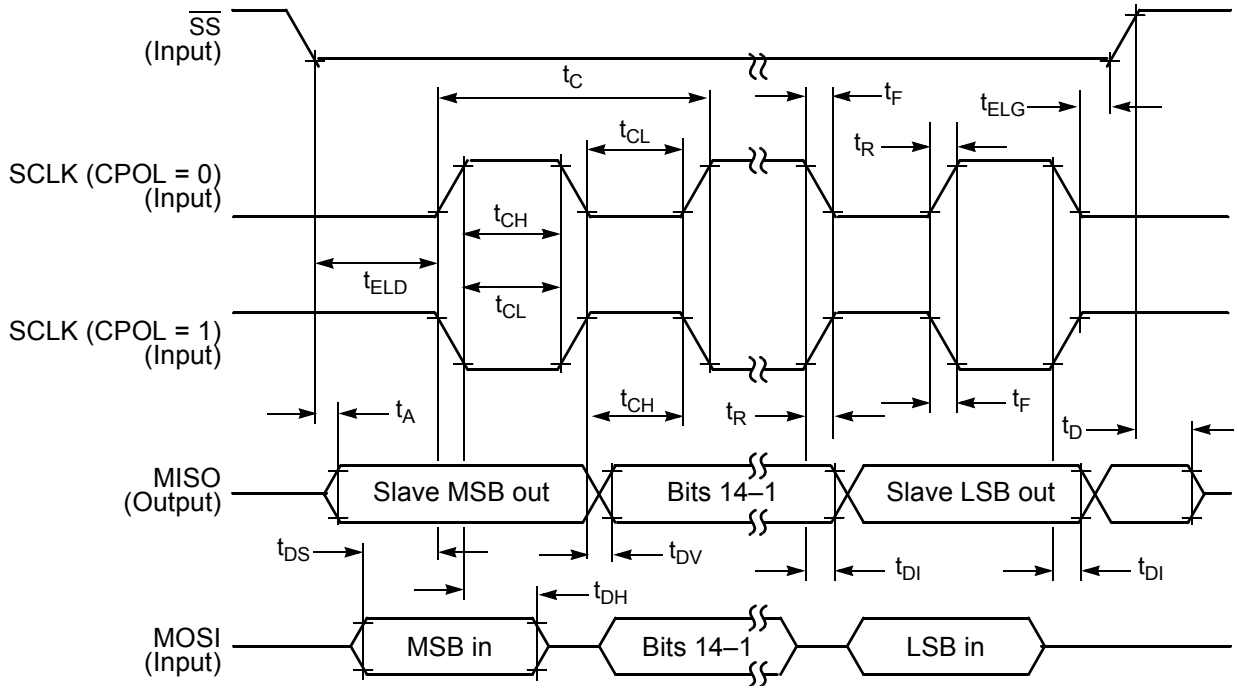

Figure 10-12 SPI Slave Timing (CPHA = 0)

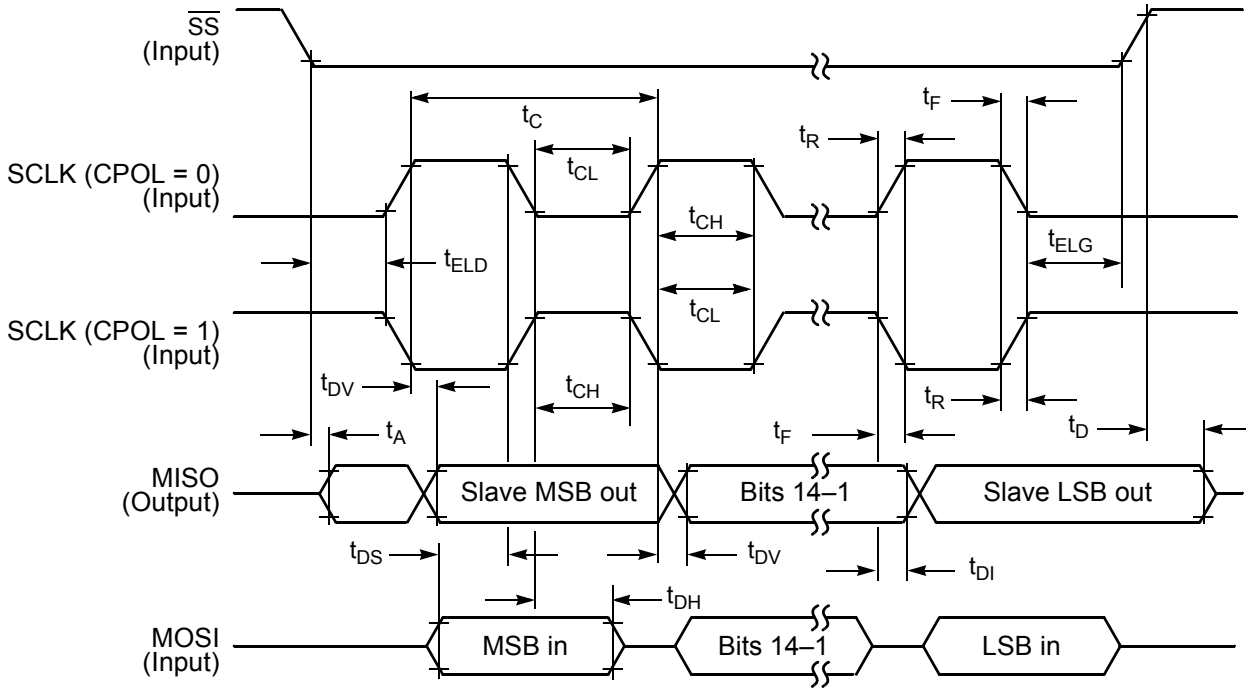

Figure 10-13 SPI Slave Timing (CPHA = 1)

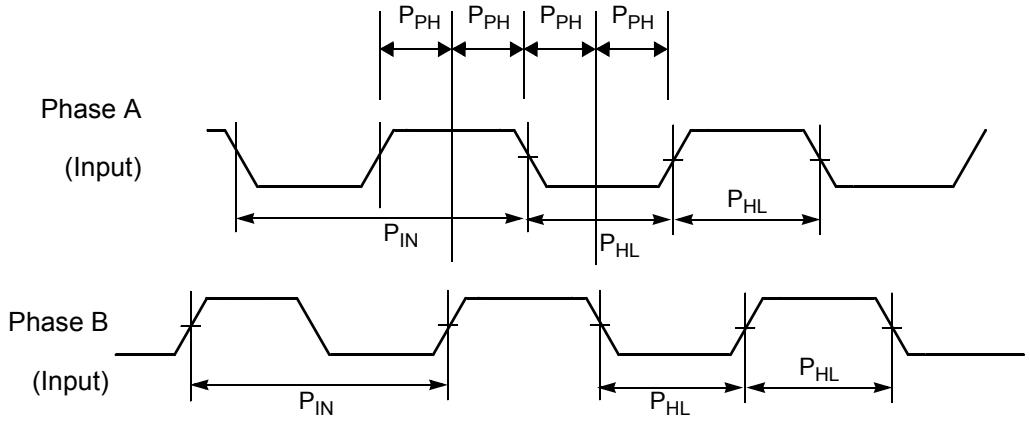

Figure 10-15 Quadrature Decoder Timing

10.13 Serial Communication Interface (SCI) Timing

Table 10-21 SCI Timing[1]

Characteristic	Symbol	Min	Max	Unit	See Figure
Baud Rate[2]	BR	—	(f_{MAX}/16)	Mbps	—
RXD[3] Pulse Width	RXD_{PW}	0.965/BR	1.04/BR	ns	10-16
TXD[4] Pulse Width	TXD_{PW}	0.965/BR	1.04/BR	ns	10-17

1. Parameters listed are guaranteed by design.
2. f_{MAX} is the frequency of operation of the system clock, ZCLK, in MHz, which is 60MHz for the 56F8357 device and 40MHz for the 56F8157 device.
3. The RXD pin in SCI0 is named RXD0 and the RXD pin in SCI1 is named RXD1.
4. The TXD pin in SCI0 is named TXD0 and the TXD pin in SCI1 is named TXD1.

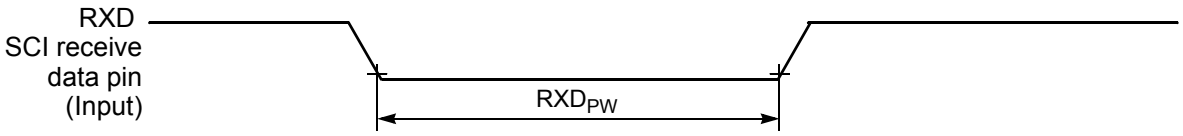

Figure 10-16 RXD Pulse Width

Figure 10-17 TXD Pulse Width

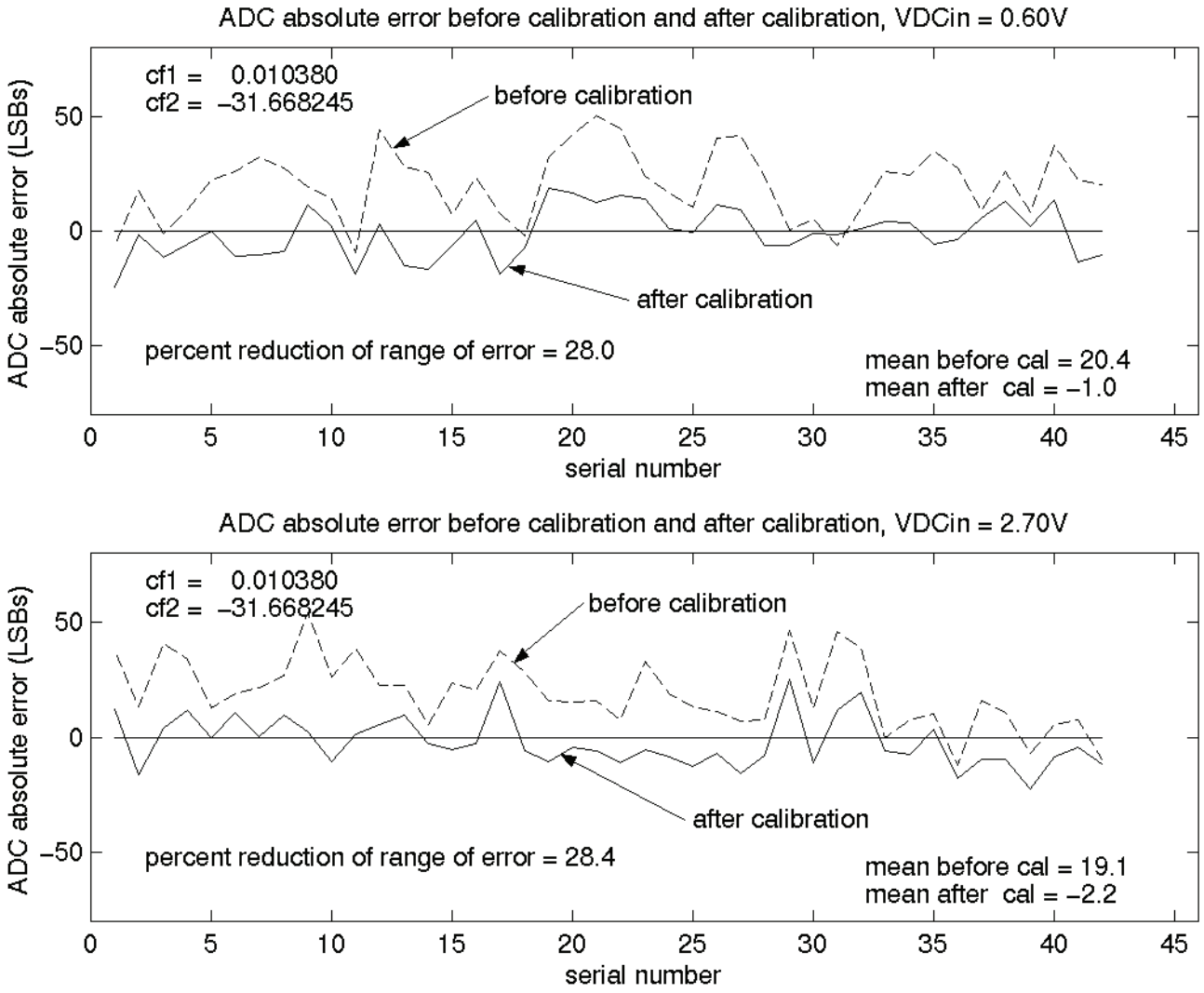

Figure 10-22 ADC Absolute Error Over Processing and Temperature Extremes Before and After Calibration for VDC_{in} = 0.60V and 2.70V

Note: The absolute error data shown in the graphs above reflects the effects of both gain error and offset error. The data was taken on 14 parts: three each from three processing corner lots and two from the fourth processing corner lot, as well as three from one nominally processed lot, each at three temperatures: -40°C, 27°C, and 150°C (giving the 42 data points shown above), for two input DC voltages: 0.60V and 2.70V. The data indicates that for the given population of parts, calibration significantly reduced (by as much as 28%) the collective variation (spread) of the absolute error of the population. It also significantly reduced (by as much as 80%) the mean (average) of the absolute error and thereby brought it significantly closer to the ideal value of zero. Although not guaranteed, it is believed that calibration will produce results similar to those shown above for any population of parts, including those which represent processing and temperature extremes.

C, the internal [dynamic component], is classic $C*V^2*F$ CMOS power dissipation corresponding to the 56800E core and standard cell logic.

D, the external [dynamic component], reflects power dissipated on-chip as a result of capacitive loading on the external pins of the chip. This is also commonly described as $C*V^2*F$, although simulations on two of the IO cell types used on the device reveal that the power-versus-load curve does have a non-zero Y-intercept.

Table 10-25 IO Loading Coefficients at 10MHz

	Intercept	Slope
PDU08DGZ_ME	1.3	0.11mW / pF
PDU04DGZ_ME	1.15mW	0.11mW / pF

Power due to capacitive loading on output pins is (first order) a function of the capacitive load and frequency at which the outputs change. **Table 10-25** provides coefficients for calculating power dissipated in the IO cells as a function of capacitive load. In these cases:

TotalPower = Σ((Intercept +Slope*Cload)*frequency/10MHz)

where:

- Summation is performed over all output pins with capacitive loads
- TotalPower is expressed in mW
- Cload is expressed in pF

Because of the low duty cycle on most device pins, power dissipation due to capacitive loads was found to be fairly low when averaged over a period of time. The one possible exception to this is if the chip is using the external address and data buses at a rate approaching the maximum system rate. In this case, power from these buses can be significant.

E, the external [static component], reflects the effects of placing resistive loads on the outputs of the device. Sum the total of all V^2/R or IV to arrive at the resistive load contribution to power. Assume V = 0.5 for the purposes of these rough calculations. For instance, if there is a total of 8 PWM outputs driving 10mA into LEDs, then P = 8*.5*.01 = 40mW.

In previous discussions, power consumption due to parasitics associated with pure input pins is ignored, as it is assumed to be negligible.

- Consider all device loads as well as parasitic capacitance due to PCB traces when calculating capacitance. This is especially critical in systems with higher capacitive loads that could create higher transient currents in the V_{DD} and V_{SS} circuits.
- Take special care to minimize noise levels on the V_{REF}, V_{DDA} and V_{SSA} pins
- Designs that utilize the $\overline{\text{TRST}}$ pin for JTAG port or EOnCE module functionality (such as development or debugging systems) should allow a means to assert $\overline{\text{TRST}}$ whenever $\overline{\text{RESET}}$ is asserted, as well as a means to assert $\overline{\text{TRST}}$ independently of $\overline{\text{RESET}}$. Designs that do not require debugging functionality, such as consumer products, should tie these pins together.
- Because the Flash memory is programmed through the JTAG/EOnCE port, the designer should provide an interface to this port to allow in-circuit Flash programming

12.3 Power Distribution and I/O Ring Implementation

Figure 12-1 illustrates the general power control incorporated in the 56F8357/56F8157. This chip contains two internal power regulators. One of them is powered from the $V_{DDA\_OSC\_PLL}$ pin and cannot be turned off. This regulator controls power to the internal clock generation circuitry. The other regulator is powered from the V_{DD_IO} pins and provides power to all of the internal digital logic of the core, all peripherals and the internal memories. This regulator can be turned off, if an external V_{DD_CORE} voltage is externally applied to the V_{CAP} pins.

In summary, the entire chip can be supplied from a single 3.3 volt supply if the large core regulator is enabled. If the regulator is not enabled, a dual supply 3.3V/2.5V configuration can also be used.

Notes:

- Flash, RAM and internal logic are powered from the core regulator output
- $V_{PP}1$ and $V_{PP}2$ are not connected in the customer system
- All circuitry, analog *and* digital, shares a common V_{SS} bus

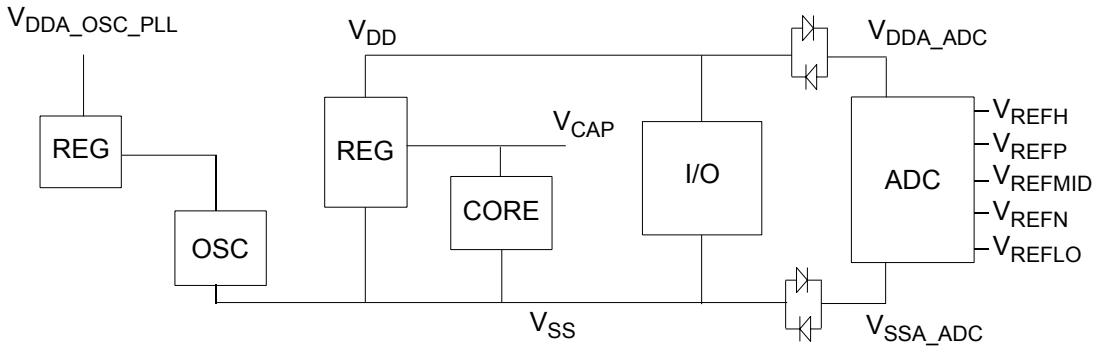

Figure 12-1 Power Management

Part 13 Ordering Information

Table 13-1 lists the pertinent information needed to place an order. Consult a Freescale Semiconductor sales office or authorized distributor to determine availability and to order parts.

Table 13-1 Ordering Information

Part	Supply Voltage	Package Type	Pin Count	Frequency (MHz)	Ambient Temperature Range	Order Number
MC56F8357	3.0–3.6 V	Low-Profile Quad Flat Pack (LQFP)	160	60	-40° to + 105° C	MC56F8357VPY60
MC56F8157	3.0–3.6 V	Low-Profile Quad Flat Pack (LQFP)	160	60	-40° to + 105° C	MC56F8157VPY
MC56F8357	3.0–3.6 V	Low-Profile Quad Flat Pack (LQFP)	160	60	-40° to + 105° C	MC56F8357VPYE*
MC56F8357	3.0–3.6 V	Low-Profile Quad Flat Pack (LQFP)	160	60	-40° to + 125° C	MC56F8357MPYE*
MC56F8157	3.0–3.6 V	Low-Profile Quad Flat Pack (LQFP)	160	60	-40° to + 105° C	MC56F8157VPYE*
MC56F8357	3.0–3.6 V	Mold Array Process Ball Grid Array (MAPBGA)	160	60	-40° to + 105° C	MC56F8357VVF*

*This package is RoHS compliant.